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Trench-based Schottky Diode, 500 mA, 20 V

NSR05201MX4

These Trench Schottky diodes are optimized for low forward voltage drop and low leakage current that offers the most optimal power dissipation in applications. They are housed in space saving micro-packaging ideal for space constrained applications.

Features

- Smallest Package Available (01005); 0.445 x 0.24mm
- 500 mA of Continuous Forward Current
- Low Forward Voltage Drop 350 mV (Typical) @ $I_F = 100 \text{ mA}$
- Low Reverse Current 40 μ A (Typical) @ $V_R = 20 \text{ V}$
- Very Low Reverse Recovery Time 8 ns Maximum
- Low Capacitance 20 pF Typical

Typical Applications

- Mobile and Wearable Devices
- Battery Chargers
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

MAXIMUM RATINGS

	Rating	Symbol	Value	Unit
Forward Current	(DC)	I _F	500	mA
Reverse Voltage		V_{R}	20	V
Repetitive Peak Forward Current (Pulse Wave = 1 sec, Duty Cycle = 66%)		I _{FRM}	1.0	Α
ESD Rating:	Human Body Model Machine Model	ESD	>8.0 >400	kV V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



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MARKING DIAGRAM



X4DFN2 (01005) CASE 718AA



T = Specific Device Code

M = Date Code

ORDERING INFORMATION

Device	Package	Shipping†
NSR05201MX4T5G	X4DFN2 (Pb-Free)	10000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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NSR05201MX4

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D	614.9 203	°C/W mW
Thermal Resistance Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA} P _D	239.4 522	°C/W mW
Junction Temperature Range	TJ	-55 to +125	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C
Lead Solder Temperature - Maximum (10 seconds)	TL	260	°C

- 1. Mounted onto a 4 in² FR-4 board 10 mm² 1 oz. Cu 0.06' thick single-sided. Operating to steady state.
- 2. Mounted onto a 4 in² FR-4 board 2 cm² 1 oz. Cu 0.06' thick single-sided. Operating to steady state.

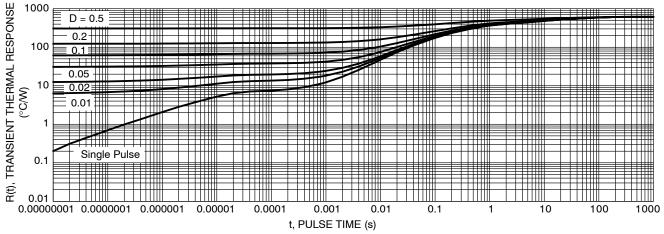


Figure 1. Thermal Response (Note 1)

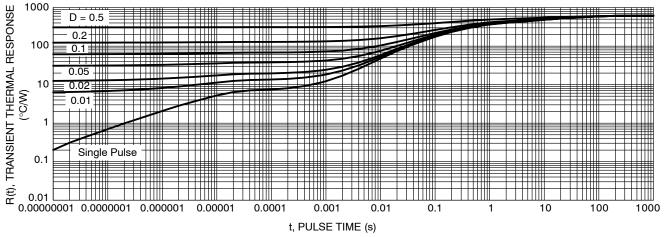


Figure 2. Thermal Response (Note 2)

NSR05201MX4

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 7 V) (V _R = 20 V)	I _R		5.0 40	60 110	μΑ
Forward Voltage (I _F = 100 mA) (I _F = 200 mA) (I _F = 500 mA)	V _F		350 400 450	480 530 600	mV
Total Capacitance (V _R = 5.0 V, f = 1 MHz)	C _T		20		pF
Reverse Recovery Time (I _F = I _R = 10 mA, I _{R(REC)} = 1.0 mA)	t _{rr}			8.0	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

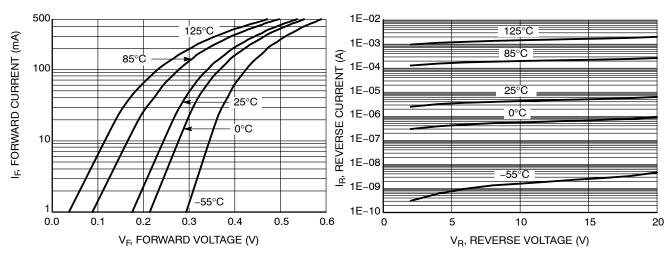


Figure 3. Forward Voltage

Figure 4. Leakage Current

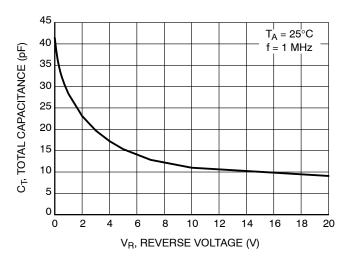
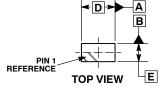


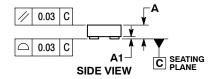
Figure 5. Total Capacitance

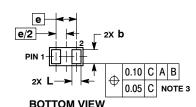
X4DFN2, 0.445x0.24, 0.27P CASE 718AA **ISSUE A**



DATE 21 MAR 2017







NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 CONTROLLING DIMENSION: MILLIMETERS.

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	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.15	0.18	0.21	
A1			0.03	
b	0.170	0.185	0.200	
D	0.415	0.445	0.475	
Е	0.210	0.240	0.270	
е	0.270 BSC			
L	0.105	0.120	0.135	

GENERIC MARKING DIAGRAMS*

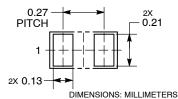




X = Specific Device Code

*This information is generic. Please refer to device data sheet for actual part marking. Some products may not follow the Generic Marking.

RECOMMENDED **MOUNTING FOOTPRINT***



See Application Note AND8398/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	X4DFN2, 0.445X0.24, 0.27F		PAGE 1 OF 1	

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